

**MODULE CONFIGURATIONS**

Viking Part Number	Capacity	Module Configuration	Device Configuration	Device Package	Module Ranks	Performance	CAS Latency
VR5DU646418EBPyzT	512MB	64Mx64	64M x 8 (8)	FBGA	1	PC2-3200	CL3 (3-3-3)
VR5DU646418EBSyzT	512MB	64Mx64	64M x 8 (8)	FBGA	1	PC2-4200	CL4 (4-4-4)
VR5DU646418EBWyzT	512MB	64Mx64	64M x 8 (8)	FBGA	1	PC2-5300	CL5 (5-5-5)
VR5DU646418EBYyzT	512MB	64Mx64	64M x 8 (8)	FBGA	1	PC2-6400	CL5 (5-5-5)
VR5DU646418EBZyzT	512MB	64Mx64	64M x 8 (8)	FBGA	1	PC2-6400	CL6 (6-6-6)
VR5DU286418EBPyzT	1GB	128Mx64	64M x 8 (16)	FBGA	2	PC2-3200	CL3 (3-3-3)
VR5DU286418EBSyzT	1GB	128Mx64	64M x 8 (16)	FBGA	2	PC2-4200	CL4 (4-4-4)
VR5DU286418EBWyzT	1GB	128Mx64	64M x 8 (16)	FBGA	2	PC2-5300	CL5 (5-5-5)
VR5DU286418EBYyzT	1GB	128Mx64	64M x 8 (16)	FBGA	2	PC2-6400	CL5 (5-5-5)
VR5DU286418EBZyzT	1GB	128Mx64	64M x 8 (16)	FBGA	2	PC2-6400	CL6 (6-6-6)
VR5DU286418FBPyzT	1GB	128Mx64	128M x 8 (8)	FBGA	1	PC2-3200	CL3 (3-3-3)
VR5DU286418FBSyzT	1GB	128Mx64	128M x 8 (8)	FBGA	1	PC2-4200	CL4 (4-4-4)
VR5DU286418FBWyzT	1GB	128Mx64	128M x 8 (8)	FBGA	1	PC2-5300	CL5 (5-5-5)
VR5DU286418FBYyzT	1GB	128Mx64	128M x 8 (8)	FBGA	1	PC2-6400	CL5 (5-5-5)
VR5DU286418FBZyzT	1GB	128Mx64	128M x 8 (8)	FBGA	1	PC2-6400	CL6 (6-6-6)
VR5DU566418GBPyzT	2GB	256Mx64	256M x 8 (8)	FBGA	1	PC2-3200	CL3 (3-3-3)
VR5DU566418GBSyzT	2GB	256Mx64	256M x 8 (8)	FBGA	1	PC2-4200	CL4 (4-4-4)
VR5DU566418GBWyzT	2GB	256Mx64	256M x 8 (8)	FBGA	1	PC2-5300	CL5 (5-5-5)
VR5DU566418GBYyzT	2GB	256Mx64	256M x 8 (8)	FBGA	1	PC2-6400	CL5 (5-5-5)
VR5DU566418GBZyzT	2GB	256Mx64	256M x 8 (8)	FBGA	1	PC2-6400	CL6 (6-6-6)
VR5DU566418FBPyzT	2GB	256Mx64	128M x 8 (16)	FBGA	2	PC2-3200	CL3 (3-3-3)
VR5DU566418FBSyzT	2GB	256Mx64	128M x 8 (16)	FBGA	2	PC2-4200	CL4 (4-4-4)
VR5DU566418FBWyzT	2GB	256Mx64	128M x 8 (16)	FBGA	2	PC2-5300	CL5 (5-5-5)
VR5DU566418FBYyzT	2GB	256Mx64	128M x 8 (16)	FBGA	2	PC2-6400	CL5 (5-5-5)
VR5DU566418FBZyzT	2GB	256Mx64	128M x 8 (16)	FBGA	2	PC2-6400	CL6 (6-6-6)
VR5DU126418GBPyzT	4GB	512Mx64	256M x 8 (16)	FBGA	2	PC2-3200	CL3 (3-3-3)
VR5DU126418GBSyzT	4GB	512Mx64	256M x 8 (16)	FBGA	2	PC2-4200	CL4 (4-4-4)
VR5DU126418GBWyzT	4GB	512Mx64	256M x 8 (16)	FBGA	2	PC2-5300	CL5 (5-5-5)
VR5DU126418GBYyzT	4GB	512Mx64	256M x 8 (16)	FBGA	2	PC2-6400	CL5 (5-5-5)
VR5DU126418GBZyzT	4GB	512Mx64	256M x 8 (16)	FBGA	2	PC2-6400	CL6 (6-6-6)

**Notes**

Suffix "yz" refers to DRAM vendor and Die revision

**Features**

- 200 pin SO-DIMM
- Single 1.8V ± 0.1V Power Supply
- Programmable CAS Latency: 3, 4, 5, 6
- Burst Length (4, 8)
- Burst type (Sequential & Interleave)
- Auto & Self-Refresh.
- 8k/64ms Refresh Period.
- Differential CLK (#CLK) inputs.
- On-die termination (ODT)
- Off-chip driver (OCD) impedance calibration
- Serial Presence Detect with EEPROM.
- RoHS Compliant\* (see last page)
- Industrial Temperature (-40C to +95C)

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**PIN CONFIGURATIONS**

Pin		Pin		Pin		Pin		Pin		Pin		Pin		Pin	
1	VREF	26	DM1	51	DQS2	76	DQ31	101	A1	126	DQ37	151	DQ42	176	DQ55
2	GND	27	GND	52	DM2	77	GND	102	A0	127	GND	152	DQ46	177	GND
3	GND	28	GND	53	GND	78	GND	103	VDD	128	GND	153	DQ43	178	GND
4	DQ4	29	#DQS1	54	GND	79	CKE0	104	VDD	129	#DQS4	154	DQ47	179	DQ56
5	DQ0	30	CK0	55	DQ18	80	**CKE1	105	A10/AP	130	DM4	155	GND	180	DQ60
6	DQ5	31	DQS1	56	DQ22	81	VDD	106	BA1	131	DQS4	156	GND	181	DQ57
7	DQ1	32	#CK0	57	DQ19	82	VDD	107	BA0	132	GND	157	DQ48	182	DQ61
8	GND	33	GND	58	DQ23	83	NC	108	#RAS	133	GND	158	DQ52	183	GND
9	GND	34	GND	59	GND	84	*A15	109	#WE	134	DQ38	159	DQ49	184	GND
10	DM0	35	DQ10	60	GND	85	†BA2	110	#S0	135	DQ34	160	DQ53	185	DM7
11	#DQS0	36	DQ14	61	DQ24	86	‡A14	111	VDD	136	DQ39	161	GND	186	#DQS7
12	GND	37	DQ11	62	DQ28	87	VDD	112	VDD	137	DQ35	162	GND	187	GND
13	DQS0	38	DQ15	63	DQ25	88	VDD	113	#CAS	138	GND	163	NC	188	DQS7
14	DQ6	39	GND	64	DQ29	89	A12	114	ODT0	139	GND	164	CK1	189	DQ58
15	GND	40	GND	65	GND	90	A11	115	**S1	140	DQ44	165	GND	190	GND
16	DQ7	41	GND	66	GND	91	A9	116	A13	141	DQ40	166	#CK1	191	DQ59
17	DQ2	42	GND	67	DM3	92	A7	117	VDD	142	DQ45	167	#DQS6	192	DQ62
18	GND	43	DQ16	68	#DQS3	93	A8	118	VDD	143	DQ41	168	GND	193	GND
19	DQ3	44	DQ20	69	NC	94	A6	119	**ODT1	144	GND	169	DQS6	194	DQ63
20	DQ12	45	DQ17	70	DQS3	95	VDD	120	NC	145	GND	170	DM6	195	SDA
21	VSS	46	DQ21	71	GND	96	VDD	121	GND	146	#DQS5	171	GND	196	GND
22	DQ13	47	GND	72	GND	97	A5	122	GND	147	DM5	172	GND	197	SCL
23	DQ8	48	GND	73	DQ26	98	A4	123	DQ32	148	DQS5	173	DQ50	198	SA0
24	GND	49	#DQS2	74	DQ30	99	A3	124	DQ36	149	GND	174	DQ54	199	VDDSPD
25	DQ9	50	#EVENT	75	DQ27	100	A2	125	DQ33	150	GND	175	DQ51	200	SA1

\*Pins are not used on module.  
 \*\* Pins are used on 2 rank modules.  
 † Pins are used on 1Gb based modules.  
 ‡ Pins are used on 2Gb based modules.

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**PIN FUNCTION DESCRIPTION**

SYMBOL	TYPE	POLARITY	DESCRIPTION
CK0, CK1 /CK0, /CK1	IN	Positive Edge Negative Edge	Clock: CK and /CK are differential clock inputs. All addresses and control input signals are sampled on the crossing of the positive edge of CK and negative edge of /CK. Output data (DQs, DQS and /DQS) is referenced to the crossings of CK and /CK.
CKE0 ~ CKE1	IN	Active High	CKE HIGH activates, and CKE LOW deactivates internal clock signals, and device input buffers and output drivers of the SDRAMs. Taking CKE LOW provides PRECHARGE POWER-DOWN and SELF REFRESH operation (all banks idle), or ACTIVE POWER DOWN (row ACTIVE in any bank)
/S0 ~ /S1	IN	Active Low	Enables the associated SDRAM command decoder when low and disables decoder when high. When decoder is disabled, new commands are ignored and previous operations continue. These input signals also disable all outputs (except CKE and ODT) of the register(s) on the DIMM when both inputs are high. When both S[0:1] are high, all register outputs (except CKE, ODT and Chip select) remain in the previous state.
ODT0 ~ ODT1	IN	Active High	On-Die Termination control signals
/RAS, /CAS, /WE	IN	Active Low	CAS, WE When sampled at the positive rising edge of the clock, /CAS, /RAS, and /WE define the operation to be executed by the SDRAM.
VREF	Supply		Reference voltage for SSTL18 inputs
VDD	Supply		Isolated power supply for the DDR SDRAM output buffers to provide improved noise immunity
BA [2:0]	IN	-	Selects which SDRAM bank of four or eight is activated.
A [14:0]	IN	-	During a Bank Activate command cycle, Address defines the row address. During a Read or Write command cycle, Address defines the column address. In addition to the column address, AP is used to invoke autoprecharge operation at the end of the burst read or write cycle. If AP is high, autoprecharge is selected and BA0, BA1, BA2 defines the bank to be precharged. If AP is low, autoprecharge is disabled. During a Precharge command cycle, AP is used in conjunction with BA0, BA1, and BA2 to control which bank(s) to precharge. If AP is high, all banks will be precharged regardless of the state of BA0 or BA1 or BA2. If AP is low, BA0 and BA1 and BA2 are used to define which bank to precharge.
DQ [63:0]	I/O	-	Data Input/Output pins
DM [7:0]	IN	Active High	Masks write data when high, issued concurrently with input data.
VDD, GND	Supply	-	Power and ground for the DDR SDRAM input buffers and core logic.
DQS [7:0]	I/O	Positive Edge	Positive line of the differential data strobe for input and output data.
/DQS [7:0]	I/O	Negative Edge	Negative line of the differential data strobe for input and output data.
/EVENT	Out	-	The optional EVENT pin is reserved for use to flag critical module temperatures and is used in conjunction with a SPD temperature sensing option.
SA [1:0]	IN	-	These signals are tied at the system planar to either VSS or VDDSPD to configure the serial SPD EEPROM address range.
SDA	I/O	-	This bi-directional pin is used to transfer data into or out of the SPD EEPROM. A resistor must be connected from the SDA bus line to VDDSPD on the system planar to act as a pull-up.
SCL	IN	-	This signal is used to clock data into and out of the SPD EEPROM. A resistor may be connected from the SCL bus time to VDDSPD on the system planar to act as a pull-up.
VDDSPD	Supply	-	Serial EEPROM positive power supply (wired to a separate power pin at the connector, which supports from 1.7 Volt to 3.6 Volt (nominal 1.8 Volt, 2.5 Volt and 3.3 Volt) operations.

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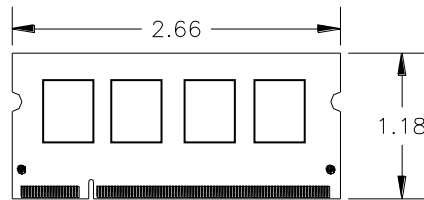
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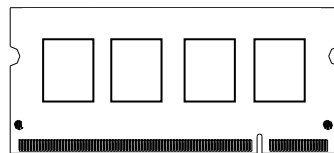
**MECHANICAL OUTLINE**

All dimensions are in inches with a tolerance of +/- 0.05 unless otherwise specified.

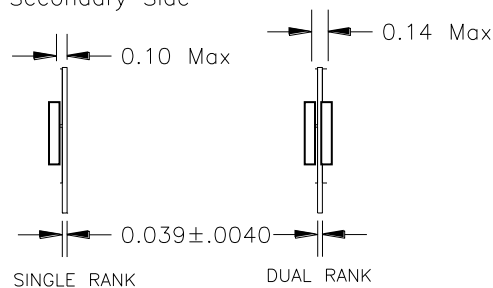
Single Rank



Primary Side



Secondary Side



SINGLE RANK

DUAL RANK

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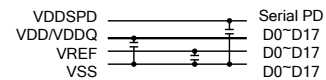
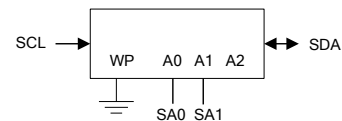
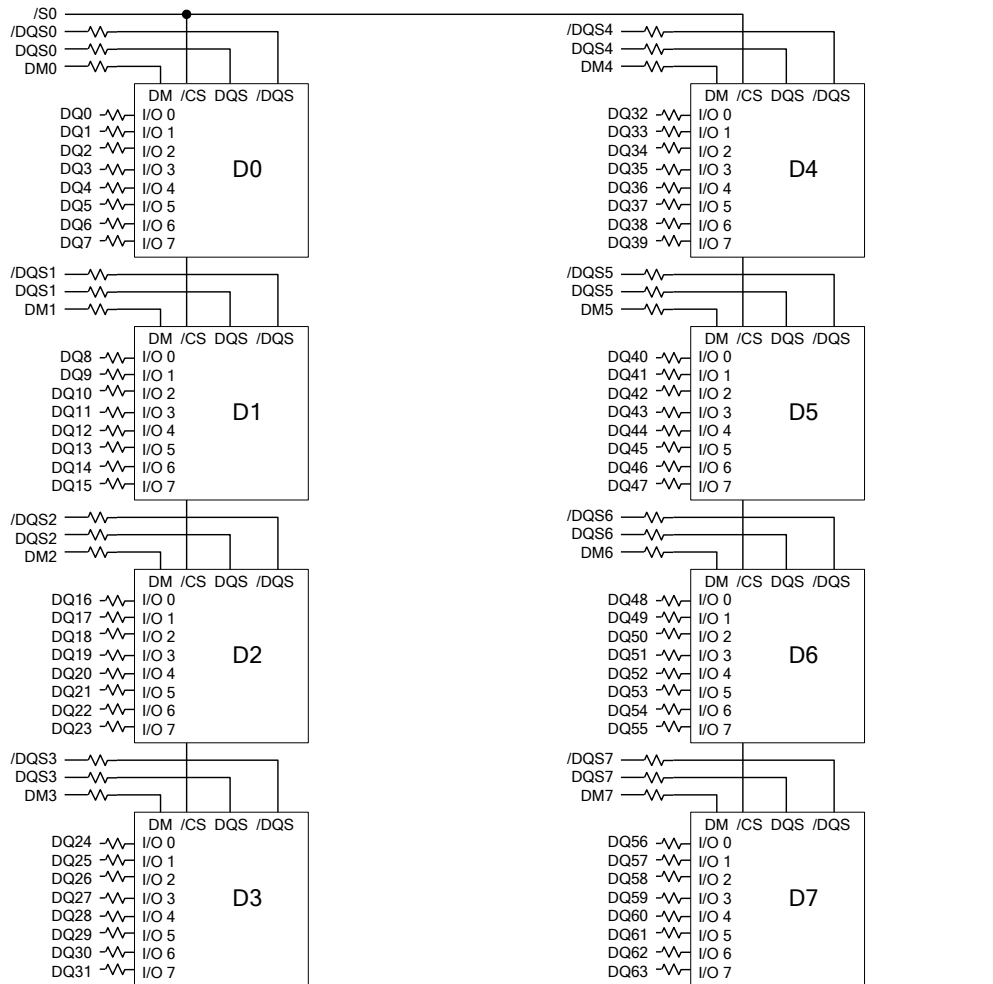
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**FUNCTIONAL BLOCK DIAGRAM SINGLE RANK**



- BA0~BA2 → BA0~BA2: SDRAMs D0~D7
- A0~An → A0~An: SDRAMs D0~D7
- CKE0 → CKE0: SDRAMs D0~D7
- /RAS → /RAS: SDRAMs D0~D7
- /CAS → /CAS: SDRAMs D0~D7
- /WE → /WE: SDRAMs D0~D7
- ODT0 → ODT0: SDRAMs D0~D7

Notes:  
1. Unless otherwise noted, resistor values are 22 Ohms +/- 5%

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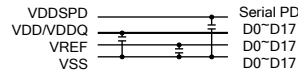
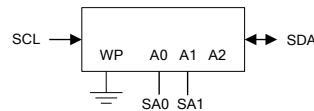
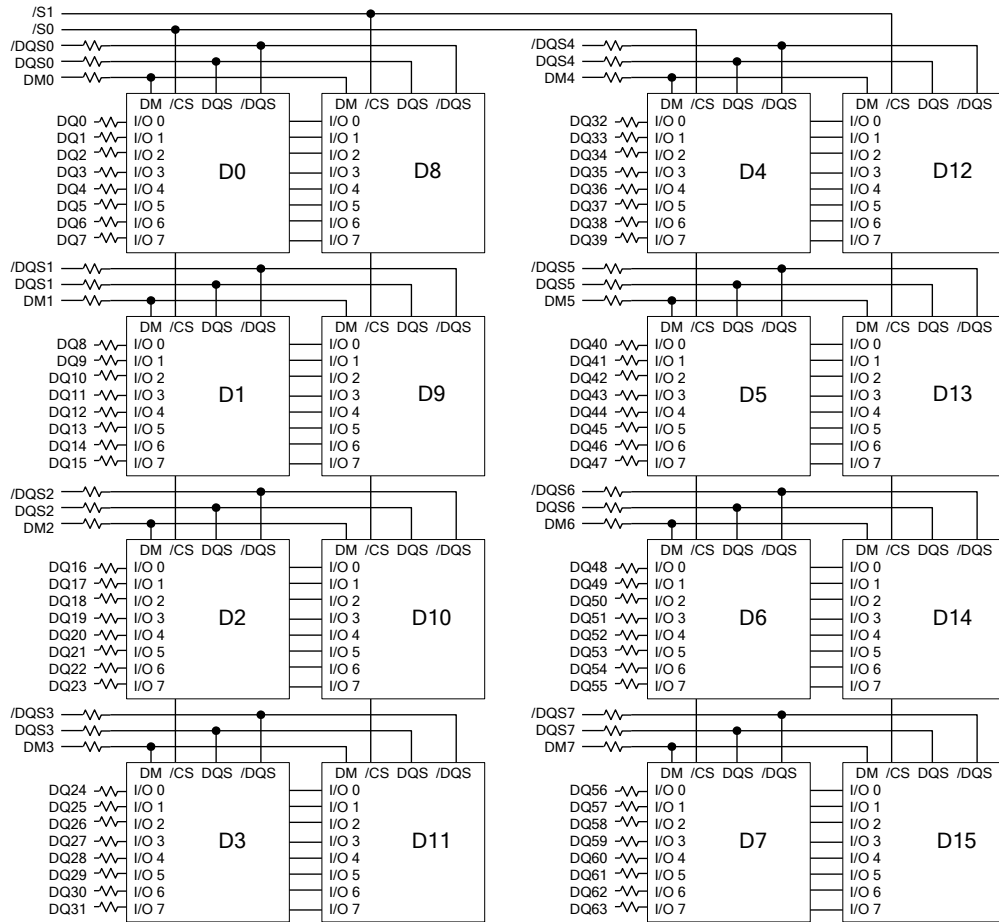
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**FUNCTIONAL BLOCK DIAGRAM DUAL RANK**



- BA0~BA2 → BA0~BA2: SDRAMs D0~D15
- A0~An → A0~An: SDRAMs D0~D15
- CKE0 → CKE0: SDRAMs D0~D7
- CKE1 → CKE1: SDRAMs D8~D15
- /RAS → /RAS: SDRAMs D0~D15
- /CAS → /CAS: SDRAMs D0~D15
- /WE → /WE: SDRAMs D0~D15
- ODT0 → ODT0: SDRAMs D0~D7
- ODT1 → ODT1: SDRAMs D8~D15

Notes:  
1. Unless otherwise noted, resistor values are 22 Ohms +/- 5%

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**Pb-FREE**

### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Voltage on any pin relative to GND	Vin, Vout	-0.5 ~ 2.3	V
Voltage on VDD supply relative to GND	VDD	-1.0 ~ 2.3	V
Voltage on VDDQ supply relative to GND	VDDQ	-0.5 ~ 2.3	V
Storage temperature	TSTG	-55 ~ +100	°C

**Note:** Permanent device damage may occur if 'ABSOLUTE MAXIMUM RATINGS' are exceeded. Functional operation should be restricted to recommended operating condition. Exposure to higher than recommended voltage for extended periods of time could affect device reliability.

### DC OPERATING CONDITIONS AND CHARACTERISTICS (SSTL\_1.8)

Recommended operating conditions (Voltages referenced to GND, Tcase = -40 to 85°C)

Parameter	Symbol	Min.	Max.	Unit	Notes
Case Temperature (Industrial Temperature)	Tcase	-40	85	°C	
Supply voltage	VDD	1.7	1.9	V	
Supply voltage for DQ, DQS	VDDQ	1.7	1.9	V	
Input reference voltage	VREF	0.49 x VDDQ	0.51 x VDDQ	V	1, 2
EEPROM Supply Voltage	VDDSPD	1.7	3.6	V	
Input high voltage	VIH	VREF + 0.125	VDDQ + 0.3	V	
Input low voltage	VIL	-0.3	VREF - 0.125	V	
Input leakage current	IIL	-40	40	µA	3
Output leakage current	IOL	-5	5	µA	4
Input leakage current	IIL	-80	80	µA	3
Output leakage current	IOL	-10	10	µA	4

- Note:**
1. Peak to peak AC noise on VREF may not exceed +/- 2% VREF (DC). VREF is also expected to track noise variation in VDD.
  2. For any pin under test input of  $0V \leq V_{IN} \leq VDDQ + 0.3V$ .
  3. Any input  $0V \leq V_{in} \leq VDD$ ; all other pins not under test = 0V.
  4.  $0V \leq V_{OUT} \leq VDDQ$ ; DQ and ODT disabled

### CAPACITANCE (VDD = 1.8V, TA = 25°C)

Parameter	Symbol	Min		Max		Unit	
		Single Rank	Dual Rank	Single Rank	Dual Rank		
Input capacitance (A0 ~ An, BA0 ~ BA1)	CIN1	13	21	21	37	pF	
Input capacitance (/RAS, /CAS, /WE)	CIN2	13	21	21	37	pF	
Input capacitance (CKE0 ~ *CKE1)	CIN3	13		21		pF	
Input capacitance (/S0 ~ */S1)	CIN4	13		21		pF	
Input capacitance (CK0, /CK0 ~ CK1, /CK1)	CIN5a	8	11	11	17	pF	
Input capacitance (DQS0 ~ DQS7, /DQS0 ~ /DQS7), (DM0 ~ DM7)	400MHz, 533MHz	CIN6a	7.5	10	9	13	pF
	667MHz, 800MHz	CIN6c	7.5	10	8.5	12.5	pF
Data input/output capacitance (DQ0 ~ DQ63)	400MHz, 533MHz	COUTa	7.5	10	9	13	pF
	667MHz, 800MHz	COUTc	7.5	10	8.5	12.5	pF

\*Used in dual ranked module only

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**DC CHARACTERISTICS DEFINITIONS** (Recommended operating conditions unless otherwise noted, Tcase = 0 to 85 °C)

Parameter	Symbol	Test Condition	Unit	Note	
Operating one bank active-precharge current	IDD0	tCK = tCK(IDD), tRC = tRC(IDD), tRAS = tRASmin(IDD); CKE is HIGH, /S is HIGH between valid commands; Address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 2	
Operating one bank active-read-precharge current	IDD1	IOUT = 0mA; BL = 4, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRC = tRC(IDD), tRAS = tRASmin(IDD), tRCD = tRCD(IDD); CKE is HIGH, /S is HIGH between valid commands; Address bus inputs are SWITCHING; Data pattern is same as IDD4W	mA	1, 2	
Precharge power-down current	IDD2P	All banks idle; tCK = tCK(IDD); CKE is LOW; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3	
Precharge quiet standby current	IDD2Q	All banks idle; tCK = tCK(IDD); CKE is HIGH, /S is HIGH; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	mA	1, 3	
Precharge standby current	IDD2N	All banks idle; tCK = tCK(IDD); CKE is HIGH, /S is HIGH; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3	
Active power-down current	IDD3P-F	All banks open; tCK = tCK(IDD); CKE is LOW; Other control and address bus inputs are STABLE; Data bus inputs are FLOATING	Fast PDN Exit MR(12) = 0	mA	1, 3
	IDD3P-S		Slow PDN Exit MR(12) = 1		
Active standby current	IDD3N	All banks open; tCK = tCK(IDD), tRAS = tRASmax(IDD), tRP = tRP(IDD); CKE is HIGH, /S is HIGH between valid commands; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3	
Operating burst read current	IDD4R	All banks open, Continuous burst reads, IOUT = 0mA; BL = 4, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRAS = tRASmax(IDD), tRP = tRP(IDD); CKE is HIGH, /S is HIGH between valid commands; address bus inputs are SWITCHING; Data pattern is same as IDD4W	mA	1, 2	
Operating burst write current	IDD4W	All banks open, Continuous burst writes; BL = 4, CL = CL(IDD), AL = 0; tCK = tCK(IDD), tRAS = tRASmax(IDD), tRP = tRP(IDD); CKE is HIGH, /S is HIGH between valid commands; Address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 2	
Auto refresh current	IDD5	tCK = tCK(IDD); Refresh command at every tRFC(IDD) interval; CKE is HIGH, /S is HIGH between valid commands; Other control and address bus inputs are SWITCHING; Data bus inputs are SWITCHING	mA	1, 3	
Self refresh current	IDD6	CK and /CK at 0V; CKE ≤ 0.2V; Other control and address bus inputs are FLOATING; Data bus inputs are FLOATING	mA	1, 3	
Operating bank interleave read current	IDD7	All bank interleaving reads, IOUT = 0mA; BL = 4, CL = CL(IDD), AL = tRCD(IDD)-1*tCK(IDD); tCK = tCK(IDD), tRC = tRC(IDD), tRRD = tRRD(IDD), tRCD = 1*tCK(IDD); CKE is HIGH, /S is HIGH between valid commands; Address bus inputs are STABLE during DESELECTs; Data pattern is same as IDD4R	mA	1, 2	

- Note:**
1. Calculated values are from component data. ODT disabled. IDD1, TDD4R are defined with the outputs disabled.
  2. For dual rank modules the other rank is in IDD2P Precharge Power-Down Standby Current mode.
  3. For dual rank modules both ranks are in the same IDD current mode.

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**DC CHARACTERISTICS CURRENTS SINGLE RANK 512Mb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	640	640	680	800	mA
IDD1	760	760	800	920	mA
IDD2P	64	64	64	56	mA
IDD2Q	240	240	280	400	mA
IDD2N	280	280	320	440	mA
IDD3P-F	240	240	240	320	mA
IDD3P-S	96	96	96	96	mA
IDD3N	400	400	440	560	mA
IDD4R	880	1000	1160	1640	mA
IDD4W	880	960	1120	1560	mA
IDD5	1120	1120	1200	1840	mA
IDD6	64	64	64	56	mA
IDD7	1760	1760	1760	2400	mA

**DC CHARACTERISTICS CURRENTS DUAL RANK 512Mb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	704	704	744	856	mA
IDD1	824	824	864	976	mA
IDD2P	128	128	128	112	mA
IDD2Q	480	480	560	800	mA
IDD2N	560	560	640	880	mA
IDD3P-F	480	480	480	640	mA
IDD3P-S	192	192	192	192	mA
IDD3N	800	800	880	1120	mA
IDD4R	944	1064	1224	1696	mA
IDD4W	944	1024	1184	1616	mA
IDD5	2240	2240	2400	3680	mA
IDD6	128	128	128	112	mA
IDD7	1824	1824	1824	2456	mA

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**DC CHARACTERISTICS CURRENTS SINGLE RANK 1Gb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	560	560	680	720	mA
IDD1	720	760	800	880	mA
IDD2P	56	56	56	56	mA
IDD2Q	280	320	320	400	mA
IDD2N	280	320	320	400	mA
IDD3P-F	240	240	240	320	mA
IDD3P-S	80	80	80	80	mA
IDD3N	320	360	440	480	mA
IDD4R	840	1000	1080	1280	mA
IDD4W	840	1000	1080	1280	mA
IDD5	1640	1680	1720	1880	mA
IDD6	56	56	56	56	mA
IDD7	2080	2160	2240	2680	mA

**DC CHARACTERISTICS CURRENTS DUAL RANK 1Gb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	616	616	736	776	mA
IDD1	776	816	856	936	mA
IDD2P	112	112	112	112	mA
IDD2Q	560	640	640	800	mA
IDD2N	560	640	640	800	mA
IDD3P-F	480	480	480	640	mA
IDD3P-S	160	160	160	160	mA
IDD3N	640	720	880	960	mA
IDD4R	896	1056	1136	1336	mA
IDD4W	896	1056	1136	1336	mA
IDD5	3280	3360	3440	3760	mA
IDD6	112	112	112	112	mA
IDD7	2136	2216	2296	2736	mA

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**DC CHARACTERISTICS CURRENTS SINGLE RANK 2Gb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	680	680	720	760	mA
IDD1	840	840	880	960	mA
IDD2P	120	120	120	120	mA
IDD2Q	360	360	400	440	mA
IDD2N	400	400	440	480	mA
IDD3P-F	320	320	320	400	mA
IDD3P-S	144	144	144	144	mA
IDD3N	520	520	560	640	mA
IDD4R	1200	1200	1360	1600	mA
IDD4W	1040	1040	1200	1360	mA
IDD5	2000	2000	2080	2240	mA
IDD6	120	120	120	120	mA
IDD7	2320	2320	2560	2800	mA

**DC CHARACTERISTICS CURRENTS DUAL RANK 2Gb**

Symbol	DDR2-400	DDR2-533	DDR2-667	DDR2-800	Unit
IDD0	800	800	840	880	mA
IDD1	960	960	1000	1080	mA
IDD2P	240	240	240	240	mA
IDD2Q	720	720	800	880	mA
IDD2N	800	800	880	960	mA
IDD3P-F	640	640	640	800	mA
IDD3P-S	288	288	288	288	mA
IDD3N	1040	1040	1120	1280	mA
IDD4R	1320	1320	1480	1720	mA
IDD4W	1160	1160	1320	1480	mA
IDD5	4000	4000	4160	4480	mA
IDD6	240	240	240	240	mA
IDD7	2440	2440	2680	2920	mA

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### AC INPUT TEST CONDITIONS

Parameter	Symbol	Value	Unit	Notes
Input reference voltage	VREF	0.50 * VDDQ	V	
Input signal maximum peak to peak swing	VSWING <sub>(MAX)</sub>	1.0	V	
Input signal maximum slew rate	SLEW	1.0	V/ns	1, 2

**Notes:**

1. The Input signal minimum slew rate is to be maintain over the range from VIL(DC) max to VIL(AC) min for raising edges and the range from VIH(DC) min to VIL(AC) max for falling edges.
2. AC timings are reference with input waveforms switching from VIL(AC) to VIH(AC) on the positive transition and VIH(AC) to VIL(AC) on the negative transitions.

### AC OPERATING CONDITIONS (VDD = 1.8V ± 0.1V, TOPR = 0 to 85 °C)

Parameter	Symbol	Value		Unit	Notes
		Min	Max		
Input Differential Voltage	VID(ac)	0.5	VDDQ +0.6	V	1
Input Crossing Point Voltage	VIX(ac)	0.5*VDDQ -0.175	0.5*VDDQ +0.175	V	2

**Notes:**

1. VID (AC) specifies the input differential voltage  $|V_{tr} - V_{cp}|$  required for switching, where  $V_{tr}$  is the true input (such as CK, DQS, LDQS, UDQS, RDQS) level and  $V_{cp}$  is the complementary input (such as CK#, DQS#, LDQS#, UDQS#, RDQS#). The minimum value is equal to  $V_{IH}(AC) - V_{IL}(AC)$ .
2. The typical value of  $V_{ix}(AC)$  is expected to be about 0.5 x VDDQ of the transmitting devices and  $V_{ix}(AC)$  is expected to track variations in VDDQ.

### OCD Default Characteristics

Description	Min	Nom	Max	Unit	Notes
Output Impedance	12.6	18	23.4	Ohms	1, 2
Pull-Up and Pull-Down mismatch	0	-	4	Ohms	1, 2, 3
Output slew rate	1.5	-	4.5	V/ns	1, 4, 5

**Notes:**

1. Absolute specifications:  $0^{\circ}\text{C} \leq T_{\text{case}} \leq 85^{\circ}\text{C}$ ;  $V_{\text{DD}} = 1.8\text{V} \pm 0.1\text{V}$ ,  $V_{\text{DDQ}} = 1.8\text{V} \pm 0.1\text{V}$ .
2. Impedance measurement condition for output source dc current:  $V_{\text{DDQ}} = 1.7\text{V}$ ;  $V_{\text{OUT}} = 1420\text{mV}$ ;  $(V_{\text{OUT}} - V_{\text{DDQ}})/I_{\text{oh}}$  must be less than 23.4 ohms for values of  $V_{\text{OUT}}$  between VDDQ and VDDQ-280mV. Impedance measurement condition for output sink dc current:  $V_{\text{DDQ}} = 1.7\text{V}$ ;  $V_{\text{OUT}} = 280\text{mV}$ ;  $V_{\text{OUT}}/I_{\text{ol}}$  must be less than 23.4 ohms for values of  $V_{\text{OUT}}$  between 0V and 280mV.
3. Mismatch is absolute value between pull-up and pull-dn, both are measured at same temperature and voltage.
4. Slew rate measured from  $v_{il}(ac)$  to  $v_{ih}(ac)$ .
5. The absolute value of the slew rate as measured from DC to DC is equal to or greater than the slew rate as measured from AC to AC. This is guaranteed by design and characterization.

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**AC CHARACTERISTICS** (AC operating conditions unless otherwise noted)

Symbol	Parameter	PC2-3200		PC2-4200		PC2-5300		PC2-6400		Units
		min	max	min	max	min	max	min	max	
tAC	DQ output access time from CK/CK	-600	+600	-500	+500	-450	+450	-400	400	ps
tDQSCK	DQS output access time from CK/CK	-500	+500	-450	+450	-400	+400	-350	350	ps
tCH	CK high-level width	0.45	0.55	0.45	0.55	0.45	0.55	0.45	0.55	tCK
tCL	CK low-level width	0.45	0.55	0.45	0.55	0.45	0.55	0.45	0.55	tCK
tHP	CK half period	min (tCL, tCH)		min (tCL, tCH)		min (tCL, tCH)		min (tCL, tCH)		ps
tCK	Clock cycle time, CL=x	5000	8000	3750	8000	3000	8000	2500	8000	ps
tDH(base)	DQ and DM input hold time	275	x	225	x	175	x	125	x	ps
tDS(base)	DQ and DM input setup time	150	x	100	x	100	x	50	x	ps
tIPW	Control & Address input pulse width for each input	0.6	x	0.6	x	0.6	x	0.6	x	tCK
tDIPW	DQ and DM input pulse width for each input	0.35	x	0.35	x	0.35	x	0.35	x	tCK
tHZ	Data-out high-impedance time from CK/CK	x	tAC max	x	tAC max	x	tAC max	x	tAC max	ps
tLZ(DQS)	DQS low-impedance time from CK/CK	tAC min	tAC max	tAC min	tAC max	tAC min	tAC max	tAC min	tAC max	ps
tLZ(DQ)	DQ low-impedance time from CK/CK	2*tAC min	tAC max	2*tAC min	tAC max	2*tAC min	tAC max	2*tAC min	tAC max	ps
tDQSQ	DQS-DQ skew for DQS and associated DQ signals	x	350	x	300	x	240	x	200	ps
tQHS	DQ hold skew factor	x	450	x	400	x	340	x	300	ps
tQH	DQ/DQS output hold time from DQS	tHP - tQHS	x	tHP - tQHS	x	tHP - tQHS	x	tHP - tQHS	x	ps
tDQSS	First DQS latching transition to associated clock edge	-0.25	0.25	-0.25	0.25	-0.25	0.25	-0.25	0.25	tCK
tDQSH	DQS input high pulse width	0.35	x	0.35	x	0.35	x	0.35	x	tCK
tDQSL	DQS input low pulse width	0.35	x	0.35	x	0.35	x	0.35	x	tCK
tDSS	DQS falling edge to CK setup time	0.2	x	0.2	x	0.2	x	0.2	x	tCK
tDSH	DQS falling edge hold time from CK	0.2	x	0.2	x	0.2	x	0.2	x	tCK
tMRD	Mode register set command cycle time	2	x	2	x	2	x	2	x	tCK
tWPST	Write postamble	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6	tCK
tWPRE	Write preamble	0.35	x	0.35	x	0.35	x	0.35	x	tCK
tIH(base)	Address and control input hold time	475	x	375	x	275	x	250	x	ps
tIS(base)	Address and control input setup time	350	x	250	x	200	x	175	x	ps
tRPRE	Read preamble	0.9	1.1	0.9	1.1	0.9	1.1	0.9	1.1	tCK
tRPST	Read postamble	0.4	0.6	0.4	0.6	0.4	0.6	0.4	0.6	tCK
tRRD	Active to active command period for 1kb page size products	7.5	x	7.5	x	7.5	x	7.5	x	ns
tRRD	Active to active command period for 2kb page size products	10	x	10	x	10	x	10	x	ns
tFAW	Four Bank Activate period for 1kb page size products	37.5		37.5		37.5		35		ns
tFAW	Four Bank Activate period for 2kb page size products	50		50		50		45		ns
tCCD	CAS to CAS command delay	2		2		2		2	x	tCK
tWR	Write recovery time	15	x	15	x	15	x	15	x	ns

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**AC CHARACTERISTICS**

Symbol	Parameter		PC2-3200		PC2-4200		PC2-5300		PC2-6400		Units	
			min	max	min	max	min	max	min	max		
tRC	Active to Active/Auto-Refresh command period	CL = 3	55	-	-	-	-	-	-	-	ns	
		CL = 4	-	-	60	-	-	-	-	-		
		CL = 5	-	-	-	-	60	-	57.5	-		
		CL = 6	-	-	-	-	-	-	60	-		
tRFC	Auto-Refresh to Active/Auto-Refresh command period	256Mb, 512Mb	105	70000	105	70000	105	70000	105	70000	ns	
		1Gb	127.5		127.5		127.5		127.5			
		2Gb	195		195		195		195			
tRCD	Active to Read or Write (with and without Auto-Precharge) delay	CL = 3	15	-	-	-	-	-	-	-	ns	
		CL = 4	-	-	15	-	-	-	-	-		
		CL = 5	-	-	-	-	15	-	12.5	-		
		CL = 6	-	-	-	-	-	-	15	-		
tRP	Precharge command period	CL = 3	15	-	-	-	-	-	-	-	ns	
		CL = 4	-	-	15	-	-	-	-	-		
		CL = 5	-	-	-	-	15	-	12.5	-		
		CL = 6	-	-	-	-	-	-	15	-		
tRAS	Active to Precharge command	CL = 3	40	70000	-	70000	-	70000	-	70000	ns	
		CL = 4	-		45		-		-			
		CL = 5	-		-		-		45			45
		CL = 6	-		-		-		-			45
tDAL	Auto precharge write recovery + precharge time	WR+tRP	x	WR+tRP	x	WR+tRP	x	WR+tRP	x	tCK		
tWTR	Internal write to read command delay	10	x	7.5	x	7.5	x	7.5		ns		
tRTP	Internal read to precharge command delay	7.5		7.5		7.5		7.5		ns		
tXSNR	Exit self refresh to a non-read command	tRFC + 10		tRFC + 10		tRFC + 10		tRFC + 10		ns		
tXSRD	Exit self refresh to a read command	200		200		200		200	x	tCK		
tXP	Exit precharge power down to any non-read command	2	x	2	x	2	x	2	x	tCK		
tXARD	Exit active power down to read command	2	x	2	x	2	x	2	x	tCK		
tXARDS	Exit active power down to read command (slow exit, lower power)	6 - AL		6 - AL		7 - AL		8 - AL		tCK		
t <sup>1</sup> CKE	CKE minimum pulse width (high and low pulse width)	3		3		3		3		tCK		
t <sup>1</sup> AOND	ODT turn-on delay	2	2	2	2	2	2	2	2	tCK		
t <sup>1</sup> AON	ODT turn-on	tAC(min)	tAC(max)+1	tAC(min)	tAC(max)+1	tAC(min)	tAC(max)+0.7	tAC(min)	tAC(max)+0.7	ns		
t <sup>1</sup> AONPD	ODT turn-on(Power-Down mode)	tAC(min)+2	2tCK+tAC(max)+1	tAC(min)+2	2tCK+tAC(max)+1	tAC(min)+2	2tCK+tAC(max)+1	tAC(min)+2	2tCK+tAC(max)+1	ns		
t <sup>1</sup> AOFD	ODT turn-off delay	2.5	2.5	2.5	2.5	2.5	2.5	2.5	2.5	tCK		
t <sup>1</sup> AOF	ODT turn-off	tAC(min)	tAC(max)+0.6	tAC(min)	tAC(max)+0.6	tAC(min)	tAC(max)+0.6	tAC(min)	tAC(max)+0.6	ns		
t <sup>1</sup> AOFPD	ODT turn-off (Power-Down mode)	tAC(min)+2	2.5tCK+tAC(max)+1	tAC(min)+2	2.5tCK+tAC(max)+1	tAC(min)+2	2.5tCK+tAC(max)+1	tAC(min)+2	2.5tCK+tAC(max)+1	ns		
tANPD	ODT to power down entry latency	3		3		3		3		tCK		
tAXPD	ODT power down exit latency	8		8		8		8		tCK		
tOIT	OCD drive mode output delay	0	12	0	12	0	12	0	12	ns		
tDelay	Minimum time clocks remain ON after CKE asynchronously drops LOW	tIS+tCK+tIH		tIS+tCK+tIH		tIS+tCK+tIH		tIS+tCK+tIH		ns		

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**REVISION HISTORY**

Revision	Release Date	Description of Change	Checked By (Full Name)
A	June 13, 2017	Initial release based on PS5DUxxxx18xxx_G	

**STATEMENT OF COMPLIANCE**

Viking Technology shall use commercially reasonable efforts to provide components, parts, materials, products and processes to Customer that do not contain: (i) lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) above 0.1% by weight in homogeneous material or (ii) cadmium above 0.01% by weight of homogeneous material, except as provided in any exemption(s) from RoHS requirements (including the most current version of the "Annex" to Directive 2002/95/EC of 27 January, 2003), as codified in the specific laws of the EU member countries. Viking strives to obtain appropriate contractual protections from its suppliers in connection with the RoHS Directives.

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